#### PRODUCT **PORTFOLIO**



# **Molded Components**

Structure and Superior Product Protection Combined

Are you struggling to find a way to enhance the control of moisture in your product without making any changes to the design?

# If so, CSP Technologies, Inc. has an innovative single-part solution.

CSP Technologies produces custom device components using our patented **Activ-Polymer™** technology. Molded components provide structure and protection simultaneously, enabling our customers to realize improved product performance, superior product protection, increased design flexibility, and cost efficiency.

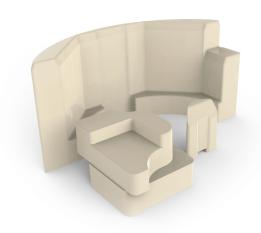
Our patented three-phase **Activ-Polymer™** technology is comprised of a network of interconnected, transmitting channels to facilitate the diffusion of gases into the polymer matrix. This channel structure enables CSP Technologies to engineer formulations that absorb or release gases from polymers. In addition, our solutions do NOT use environmentally damaging epoxies or polyurethane resins that can create chemical incompatibilities and complicate safe recycling.

Our molded components create single-part solutions that release low/no particles and are compatible with traditional forms of sterilization (e.g. gamma radiation). The molded components are available with FDA approved, pharmaceutical grade ingredients and have a Drug Master File.

#### Material science expertise

Molded components are used in a variety of applications from inhalers and transdermal drug delivery devices to point-of-care diagnostic devices, powder dispensers, industrial sensors, and various electronics. Tailored to specific applications, molded components are made with **Activ-Polymer™** technology to solve complex product challenges in various environments.

Our multi-shot molding capability with **Activ-Polymer™** technology enables us to combine multiple components and scavenging abilities into one part reducing part count and complexity for manufacturing and assembly. The molded components serve a dual role in the device; we can replace an existing component in the physical structure of your design to provide structure and protection simultaneously. The advantage: control of moisture within the environment without the need for extra space, additional parts or changes to your design.





### About CSP Technologies, Inc.

CSP Technologies, Inc. is a leader in delivering innovative, high-quality product and packaging solutions that give customers a competitive edge and consumers a better product experience.



### **Benefits**

- Reduces assembly complexity by reducing the number of components
- Design flexibility: molded components can be designed to any shape, size or geometry
- Desiccant can be molded with locating pins or holes for assembly
- Superior product protection: product can be fully surrounded by the desiccant
- Minimize size by incorporating absorption capabilities into mechanical components
- Increase product life and performance

- Control of moisture within environment without the need for extra space or changes to current design
- Molded desiccant components do not lose moisture capacity as quickly as raw desiccants in canisters or sachets

#### **Industries Served**

- Electronics
- Automotive
- Aerospace
- Industrial
- Diagnostics
- Pharmaceutical

